

C2
C3
C4
C5
hydrogenated derivatives of phenolic modified terpene resins, for example, as the resin product resulting from the condensation, in an acidic medium, of a bicyclic terpene and a phenol. NIREZ 2040, a phenolic modified terpene having a Ring and Ball softening point about 125°C and available from Arizona Chemicals, is the most preferred.--

Amend the paragraph set forth on page 7, lines 10-14, to read as follows:

C3
--The following materials were used to prepare a series of adhesives in accordance with the present invention: Irganox 1010 (available from Ciba Geigy); Nirez 2040 (available from Arizona Chemical Co.); Sylvatac 40N (available from Arizona Chemical Co.); Unitac R100 (available from Union Carbide); Kristalex 3100 (available from Hercules Co.).--

In the Claims

Amend claims 1, 6 and 8 and add new claims 10-12 as follows:

C4
C5
Claim 1. A hot melt adhesive composition comprising, by weight of the hot melt adhesive composition,

a) about 5 weight percent to about 60 weight percent of an ethylene vinyl acetate copolymer having a vinyl acetate content of about 30 weight percent to 50 weight percent and a melt index of about 700 to 4,000 dg/min;

b) about 5 weight percent to about 60 weight percent of a tackifier; and

c) about 15 weight percent to about 55 weight percent of a wax with a melting point of about 125°F to 180°F;

wherein the hot melt composition can be applied at a temperature of 200°F to 300°F.

C6
Claim 6. An adhesive according to Claim 1 wherein the wax is paraffin wax or synthetic wax.

Claim 8. A hot melt adhesive composition comprising, by weight of the hot melt adhesive composition,

a) about 35 weight percent of an ethylene vinyl acetate copolymer with about 40 weight percent vinyl acetate and having a melt index of at about 1,000;

b) about 30 weight percent of a tackifier selected from the group consisting of terpene, terpene phenolic, modified terpenes, and combinations thereof;

c) about 5 weight percent of at least one additional tackifier selected from the group consisting of pentaerythritol, hydrogenated glycerol, and combinations thereof;

d) about 30 weight percent of a wax with a melting point of about 150°F;

wherein the hot melt composition can be applied at a temperature of 200°F to 300°F.

Claim 10. An adhesive according to Claim 3 which comprises a terpene phenolic tackifier.

Claim 11. An adhesive according to Claim 1 which comprises about 35 weight percent to about 45 weight percent of an ethylene vinyl acetate copolymer.

Claim 12. A method of bonding substrates together, said method comprising applying, at an application temperature of 200°F to 300°F, the hot melt adhesive composition of claim 1 to a first substrate, bringing a second substrate in contact with the composition applied to the first substrate, whereby the first substrate becomes bonded to the second substrate.